

Title (en)
Plating bath and method

Title (de)
Galvanisierungsbad und -verfahren

Title (fr)
Procédé et bain de placage

Publication
EP 2868775 A3 20150812 (EN)

Application
EP 14191882 A 20141105

Priority
US 201314071677 A 20131105

Abstract (en)
[origin: EP2868775A2] Tin-containing electroplating baths having a combination of certain brightening agents provide tin-containing solder deposits having reduced void formation and smooth morphology.

IPC 8 full level
C25D 3/32 (2006.01); **C25D 3/60** (2006.01); **C25D 7/12** (2006.01)

CPC (source: CN EP US)
C25D 3/32 (2013.01 - CN EP US); **C25D 3/60** (2013.01 - EP US); **C25D 7/12** (2013.01 - CN EP US); **C25D 7/123** (2013.01 - CN EP US)

Citation (search report)

- [X] US 5061351 A 19911029 - COMMANDER JOHN H [US], et al
- [X] US 2011189848 A1 20110804 - EWERT INGO [DE], et al
- [AD] US 4582576 A 19860415 - OPASKAR VINCE [US], et al
- [XI] JP 4362568 B2 20091111

Cited by
CN110176441A; EP3702493A4; EP3321396A1; US11459665B2; WO2019121092A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
EP 2868775 A2 20150506; EP 2868775 A3 20150812; CN 104674312 A 20150603; JP 2015092021 A 20150514; KR 20150051926 A 20150513; TW 201533278 A 20150901; US 2015122661 A1 20150507

DOCDB simple family (application)
EP 14191882 A 20141105; CN 201410858388 A 20141105; JP 2014224805 A 20141105; KR 20140153138 A 20141105; TW 103138319 A 20141105; US 201314071677 A 20131105